12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130904000
Aizu Facility as an additional FAB source for select devices in the F05 Process
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

PCN# 20130904000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20130904000	**PCN Date:**	09/05/2013

Title:	Aizu Facility as an additional FAB source for select devices in the F05 Process

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	12/05/2013	**Estimated Sample Availability:**	Date provided at sample request.		

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This notification is to announce AIZU fabrication facility as an additional wafer FAB source for select devices in the F05 Process. The affected devices are listed in "Product Affected" section.

Currently Qualified Sites, Process, Wafer Dia.	**Additional Site, Process, Wafer Dia.**
DM5, F05 Process, 200mm	**AIZU, F05 Process, 200mm**

The F05 process was qualified in Aizu in June 2012. Qualification details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
DP1DM5	DM5	USA

Additional

Chip Site	Chip site code (20L)	Chip country code (21L)
AIZU	**CU2**	**JPN**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SM02028APTT	TMS320F28021PTT	TMS320F28023DAT	TMS320F280270DAT
SM28020PTT	TMS320F280220DAS	TMS320F28023PTS	TMS320F280270PTS
SM28021PTT	TMS320F280220DAT	TMS320F28023PTT	TMS320F280270PTT
TJF026PTT	TMS320F280220PTS	TMS320F280260DAS	TMS320F28027DAS
TMS320F280200DAS	TMS320F280220PTT	TMS320F280260DAT	TMS320F28027DASR
TMS320F280200DAT	TMS320F28022DAS	TMS320F280260PTS	TMS320F28027DAT
TMS320F280200PTS	TMS320F28022DAT	TMS320F280260PTT	TMS320F28027DATR
TMS320F280200PTT	TMS320F28022PTS	TMS320F28026DAS	TMS320F28027FPTT
TMS320F28020DAS	TMS320F28022PTSR	TMS320F28026DASR	TMS320F28027PTR
TMS320F28020DAT	TMS320F28022PTT	TMS320F28026DAT	TMS320F28027PTS
TMS320F28020PTS	TMS320F280230DAS	TMS320F28026DATR	TMS320F28027PTT
TMS320F28020PTT	TMS320F280230DAT	TMS320F28026FPTT	TMS320F28KNWMX1
TMS320F28021DAS	TMS320F280230PTS	TMS320F28026PTS	TMS320SPC0200PTT
TMS320F28021DAT	TMS320F280230PTT	TMS320F28026PTT	
TMS320F28021PTS	TMS320F28023DAS	TMS320F280270DAS	

Qualification Data: Approved 8/30/2013

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TMS320F2802XAPT

Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN
Wafer Fab Process:	F05	Wafer diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Preconditioning	MSL2/260C	540/0	-	-
*Temp Cycle	-65C/150C 500 Cycles (actual 1000 cycles)	231/0	-	-
*Autoclave	121C/96hrs (actual 168 hours)	231/0	-	-

Notes: * Test requires Moisture Preconditioning
Qualification tests "pass" on zero fails for each test

Qual Vehicle 2: TMS320F2802XADA

Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN
Wafer Fab Process:	F05	Wafer diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Preconditioning	MSL2/260C	720/0	-	-
*Temp Cycle	-65C/150C 500 Cycles(actual 750 cycles)	231/0	-	-
*Autoclave	121C/96hrs (actual 168 hours)	231/0	-	-
*High Temp Storage Life	150C, 500 hours	231/0	-	-
ESD-HBM	2000v	3/0	-	-
ESD-CDM	750v	3/0	-	-
Latchup	1.5Vdd +/-100mA 125C	6/0	-	-

Notes: * Test requires Moisture Preconditioning
Qualification tests "pass" on zero fails for each test

Reference Qual: F05 Process Qualification at Aizu

Qualification Data: Approved 06/2012					
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.					
Qual Vehicle 1: TMS320F2803XAPN					
Wafer Fab Site:	AIZU	Metallization:	TiN/AlCu/TiN		
Wafer Fab Process:	F05	Wafer diameter:	200mm		
Qualification: ☐ **Plan** ☒ **Test Results**					

Reliability Test	Conditions	Sample Size/Fail Lot#1	 Lot#2	 Lot#3
20K W/E	20K Write / Erase Cycles prior to HTSL, HTOL, RTSL	1800/0	-	-
High Temperature Op Life	125C - 1000 Hours	231/0	-	-
*High Temp Storage Life	150C Bake - 1000 Hours	231/0	-	-
Room Temp Storage Life	25C – 1000 Hours	231/0	-	-
Package Reliability			-	-
*Preconditioning	MSL3/260C	693/0	-	-
*THB	85C/85RH	231/0	-	-
*Temp Cycle	-65C/150C 500 Cycles	231/0	-	-
*Autoclave	121C/96hrs	231/0	-	-
ESD-HBM	2000v	15/0	-	-
ESD-CDM	750v	6/0	-	-
Latch up	1.5Vdd +/-100mA 125C	6/0	-	-

Notes:
* Test requires Moisture Preconditioning
Qualification tests “pass” on zero fails for each test

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com